

CLAIMS

1. A development apparatus for manufacturing a semiconductor device, said development apparatus

5 discharging a developer onto a surface of a semiconductor substrate and comprising:

a nozzle pipe for supplying said developer; and

a nozzle having a shape of a spoon with a taper
and discharging said developer supplied by said nozzle pipe
10 onto said surface of said substrate, wherein said nozzle
sprays said developer onto said surface of said substrate
at any spray angle under a low and constant pressure.

2. A development apparatus for manufacturing a semiconductor device, said development apparatus

15 discharging a developer onto a surface of a semiconductor substrate and comprising:

a nozzle pipe for supplying said developer;

a nozzle having a shape of a spoon with a taper
and discharging said developer supplied by said nozzle pipe
20 onto said surface of said substrate; and

a scanning device for simultaneously scanning
said nozzle pipe and said nozzle above said substrate in a
stationary state, wherein said nozzle sprays said developer
onto said surface of said substrate at any spray angle
25 under a low and constant pressure.

3. The development apparatus according to claim
2, which further comprises an adjusting device for
adjusting a position of said nozzle with respect to a
position of said nozzle pipe.

30 4. The development apparatus according to claim
3, wherein said adjusting device moves said nozzle with
respect to said nozzle pipe.

5. The development apparatus according to claim 3, wherein said adjusting device moves said nozzle pipe with respect to said nozzle.